PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4688211

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
GREDMANN TAIWAN LTD.	10/06/2017

RECEIVING PARTY DATA

Name:	TESSERA ADVANCED TECHNOLOGIES, INC.
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134

PROPERTY NUMBERS Total: 11

Property Type	Number
Patent Number:	6359718
Patent Number:	7002725
Patent Number:	7008821
Patent Number:	7045463
Patent Number:	7258806
Patent Number:	7361284
Patent Number:	7605970
Patent Number:	7622334
Patent Number:	7987588
Patent Number:	8030111
Patent Number:	8114699

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: patentlegal@xperi.com
Correspondent Name: XPERI CORPORATION
Address Line 1: 3025 ORCHARD PARKWAY
Address Line 4: SAN JOSE, CALIFORNIA 95134

ATTORNEY DOCKET NUMBER:	ACQ-GREDMANN

NAME OF SUBMITTER:	JENNIFER KOSTIC
SIGNATURE:	/JENNIFER KOSTIC/
DATE SIGNED:	11/14/2017

Total Attachments: 6
source=Gredmann-TATI Executed Patent Assignment#page1.tif
source=Gredmann-TATI Executed Patent Assignment#page2.tif
source=Gredmann-TATI Executed Patent Assignment#page3.tif
source=Gredmann-TATI Executed Patent Assignment#page4.tif
source=Gredmann-TATI Executed Patent Assignment#page5.tif
source=Gredmann-TATI Executed Patent Assignment#page6.tif

EXHIBIT C

FORM OF DEED OF ASSIGNMENT

THIS DEED OF ASSIGNMENT ("**Assignment**"), EFFECTIVE AS OF October 6, 2017, IS MADE BY AND BETWEEN

Gredmann Taiwan Ltd. (hereinafter "**SELLER**"), a Taiwan corporation with its principal place of business located at 11F, No. 170, Sec. 3, Minquan E. Rd., Songshan Dist., Taipei City 105, Taiwan (R.O.C); and

Tessera Advanced Technologies, Inc. (hereinafter "**BUYER**"), a Delaware corporation having a place of business at 3025 Orchard Parkway, San Jose, CA 95134.

WHEREAS:

A **SELLER** is the sole owner in respect of the patents and patent applications listed in the attached Appendix (hereinafter "the **PATENTS**"); and

B **BUYER** is desirous of acquiring all of the worldwide right, title and interest in and to the **PATENTS** and the inventions disclosed therein.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, **SELLER** has sold, assigned and transferred, and does hereby sell, assign and transfer to **BUYER** all of the worldwide right, title and interest in (i) the **PATENTS** and the inventions and improvements disclosed therein; (ii) all reissues, divisionals, continuations, continuations-in-part, extensions, renewals, reexaminations and foreign counterparts thereof, and other patents, patent applications, certificates of invention other governmental grants resulting from the **PATENTS**; (iii) all patents and applications which claim priority to or have common disclosure or common priority with any such patents or patent applications, and (iv) all rights corresponding to any of the foregoing throughout the world (including the right to claim the priority date of any of the **PATENTS** and the right to sue for and recover damages for any past, present or future infringement of the Patents, and including all benefits, privileges and powers), the same to be held and enjoyed by **BUYER** for its own use and enjoyment, and for the use and enjoyment of its successors, assigns and other legal representatives, to the end of the term or terms of said **PATENTS** granted or reissued or reexamined as fully and entirely as the same would have been held and enjoyed by **SELLER**, if this assignment and sale had not been made.

IN WITNESS WHEREOF, **SELLER** has caused these presents to be signed by its duly appointed officer having full authority to convey its property.

And if the issue date and/or patent number of any of the **PATENTS** is unknown to **ASSIGNOR** and **BUYER** at the time this Assignment is executed, **SELLER** does hereby authorize its attorneys to insert on this Assignment the issue date and patent number of said any patent when known.

SELLER hereby declares that **BUYER** may take the steps for recordal of this assignment in the sole name of **BUYER**.

SELLER hereby undertakes that it shall, without further consideration, but at the expense of **BUYER**, execute all documents and do all such acts and things as **BUYER** may in its absolute discretion consider necessary or desirable to enable Letters Patent or any other form of protection to be issued in respect of any of said **PATENTS** and the inventions disclosed therein in any part of the world and to enable or to assist **BUYER** to defend oppositions thereto, to maintain the **PATENTS** and to prosecute for the infringement thereof.

SIGNED for and on behalf of

SELLER

By ______________________ on ______2017.10.06______
(Signature) (Date)

Yeh Li-Cheng / Chairman
(Print Name and Title)

On this ___6th___ day of ___October___, 2017 before me, ______________________, personally appeared ______________________, who proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the instrument and acknowledged to me that he/she executed the same in his/her authorized capacity and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of ______________________ that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

____
(Notary Public)

PATENT
REEL: 044442 FRAME: 0963

SIGNED for and on behalf of

BUYER

by ______________________ on 10/12/2017
(Signature) (Date)

John Allen
(Print Name and Title)
Senior VP, Corporate Controller

A notary public or other officer completing this certificate verifies only the identity of the individual who signed the document to which this certificate is attached, and not the truthfulness, accuracy, or validity of that document.

State of California)
County of Santa Clara)

On October 12, 2017 before me, Jennifer Kostic, Notary Public (here insert name and title of the officer) personally appeared John Allen, who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

JENNIFER KOSTIC
Commission # 2110210
Notary Public - California
Santa Clara County
My Comm. Expires Jun 1, 2019

Signature ______________________ (Seal)

Confidential

APPENDIX – LISTED PATENTS AND PATENT APPLICATIONS

1. **United States Issued Patents and Pending Patent Applications**

United States Issued Patents

Patent Number	Filing Date (MM/DD/YYYY)	Application Number	Issue Date (MM/DD/YYYY)	Publication Number	Title
6359718	04/18/2001	09/838,061	03/19/2002		Actuating mechanism for rotating micro-mirror
7002725	03/25/2004	10/810,022	02/21/2006	20050036194	Micro grating structure
7008821	11/19/2004	10/904,621	03/07/2006	20060057775	Method of forming a wafer backside interconnecting wire
7045463	10/28/2004	10/904,188	05/16/2006	20060024965	Method of etching cavities having different aspect ratios
7258806	06/23/2006	11/426,017	08/21/2007		Method of fabricating a diaphragm of a capacitive microphone device
7361284	06/23/2006	11/426,013	04/22/2008	20070218584	Method for wafer-level package
7605970	10/29/2004	10/977,044	10/20/2009	20050123017	External cavity tunable laser system formed from MEMS corner mirror
7622334	04/09/2008	12/100,392	11/24/2009	20090061598	Wafer-level packaging cutting method capable of protecting contact pads
7987588	11/19/2008	12/273,550	08/02/2011	20090064496	Interposer for connecting plurality of chips and method for manufacturing the same
8030111	12/02/2008	12/326,355	10/04/2011	20090075406	Integration manufacturing process for MEMS device
8114699	03/28/2011	13/072,879	02/14/2012	20110174058	Integration manufacturing process for MEMS device

United States Pending Applications

None.

2. **Foreign Issued Patents and Pending Patent Applications**

None.

3. **United States and Foreign Listed Abandoned/Expired Patents and Applications**

Patent Number	Country	Filing Date (MM/DD/YYYY)	Application Number	Issue Date (MM/DD/YYYY)	Publication Number	Title
480346	TW	02/01/2001	90102091	03/21/2002		Actuating mechanism for rotating micro-mirror
I222534	TW	03/27/2003	92107004	10/21/2004	200419190	Micro actuated blazed grating
I227582	TW	11/28/2003	92133593	02/01/2005	200518410	External cavity tunable laser system formed from MEMS corner mirror array element
I229377	TW	07/30/2004	93122943	03/11/2005	200605204	Method for forming cavities having different aspect ratios
I234261	TW	09/10/2004	93127599	06/11/2005	200610119	Method of forming wafer backside interconnects

Patent Number	Country	Filing Date (MM/DD/YYYY)	Application Number	Issue Date (MM/DD/YYYY)	Publication Number	Title
I242255	TW	07/21/2004	93121813	10/21/2005	200605258	Wafer carrier
I256940	TW	06/18/2004	93117781	06/21/2006	200600447	Integration manufacturing process for MEMS element
I275416	TW	04/11/2006	95112844	03/11/2007	200738339	Micro sample heating apparatus and method of making the same
I278045	TW	03/14/2006	95108640	04/01/2007	200735235	Method for wafer-level package
I284966	TW	01/12/2006	95101278	08/01/2007	200727418	Method for wafer level package and fabricating cap structures
I305474	TW	04/10/2006	95112674	01/11/2009	200740261	Method of fabricating a diaphragm of a capacitive microphone device
I305998	TW	04/10/2006	95112673	02/01/2009	200740262	Method of fabricating a diaphragm of a capacitive microphone device
I363414	TW	01/29/2007	96103230	05/01/2012	200832664	Interposer for connecting a plurality of chips and method for manufacturing the same
I376739	TW	08/30/2007	96132321	11/11/2012	200910435	Method of wafer-level segmenting capable of protecting contact pad
7505118	US	10/12/2004	10/711,882	03/17/2009	20060017907	Wafer carrier
	US	03/28/2005	11/091,062		20050280116	Integration manufacturing process for MEMS device
7533564	US	05/02/2006	11/381,129	05/19/2009	20080060454	Micro sample heating apparatus and method of making the same
7582511	US	05/17/2006	11/434,734	09/01/2009	20070161155	Method for wafer level chip scale packaging with passive components integrated into packaging structure
7585417	US	06/23/2006	11/426,018	09/08/2009	20070235407	Method of fabricating a diaphragm of a capacitive microphone device
7598125	US	06/26/2006	11/426,573	10/06/2009	20070161158	Method for wafer level packaging and fabricating cap structures
	US	06/01/2007	11/756,634		20080182432	Interposer for connecting plurality of chips and method for manufacturing the same
8456724	US	06/17/2010	12/817,338	06/04/2013	20110310452	Biaxial scanning mirror for image forming apparatus
8310328	US	10/07/2010	12/899,836	11/13/2012	20120086537	Planar coil and method of making the same
8318511	US	01/04/2012	13/343,643	11/27/2012	20120111096	Integration manufacturing process for MEMS device
8453318	US	10/15/2012	13/651,771	06/04/2013	20130043136	Method for making a planar coil

4. **Foreign Listed Patents and Applications – Status Unknown**

Patent Number	Country	Filing Date (MM/DD/YYYY)	Application Number	Issue Date (MM/DD/YYYY)	Publication Number	Title
	TW	01/12/2006	95101214		200727370	Integrated die packaging structure and manufacturing process thereof

Confidential